

MOSFET - Power, Single N-Channel, SUPERFET® V, FAST, QFN88-4L 600 V, 61 mΩ, 41 A NTMT061N60S5H

Description

The SUPERFET V MOSFET FAST series helps maximize system efficiency by the extremely low switching losses in hard switching application. The Power88 package which is an ultraslim SMD package offers excellent switching performance by providing kelvin source configuration and lower parasitic source inductance.

Features

- $650 \text{ V} @ \text{T}_{\text{J}} = 150^{\circ}\text{C}$
- Typ. $R_{DS(on)} = 48.8 \text{ m}\Omega$
- 100% Avalanche Tested
- Pb-Free, Halogen Free/BFR Free and RoHS Compliant

Applications

- Telecom / Server Power Supplies
- EV Charger / UPS / Solar / Industrial Power Supplies

ABSOLUTE MAXIMUM RATINGS (T_J = 25°C, Unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		V_{DSS}	600	V
Gate-to-Source Voltage	DC	V_{GSS}	±30	V
	AC (f > 1 Hz)		±30	
Continuous Drain Current	T _C = 25°C	I _D	41	Α
	T _C = 100°C		25	
Power Dissipation	T _C = 25°C	P_{D}	250	W
Pulsed Drain Current (Note 1)	T _C = 25°C	I _{DM}	144	Α
Pulsed Source Current (Body Diode) (Note 1)	T _C = 25°C	I _{SM}	144	Α
Operating Junction and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C
Source Current (Body Diode)		Is	41	Α
Single Pulse Avalanche Energy	$I_L = 6.7 \text{ A},$ $R_G = 25 \Omega$	E _{AS}	376	mJ
Avalanche Current		I _{AS}	6.7	Α
Repetitive Avalanche Energy (Note 1)		E _{AR}	2.5	mJ
MOSFET dv/dt		dv/dt	120	V/ns
Peak Diode Recovery dv/dt (Note 2)			20	
Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds)		T _L	260	°C

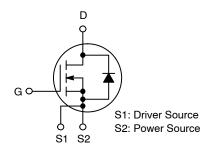
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. $I_{SD} \le 20.5$ A, di/dt ≤ 200 A/ μ s, $V_{DD} \le 400$ V, starting $T_J = 25$ °C.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
600 V	61 m Ω @ V _{GS} = 10 V	40 A

N-CHANNEL MOSFET





MARKING DIAGRAM

NTMT061 N60S5H AWLYWW

NTMT061N60S5H = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping [†]
NTMT061N60S5H	TDFN4	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case, Max.	$R_{ hetaJC}$	0.5	°C/W
Thermal Resistance, Junction-to-Ambient, Max.	$R_{ hetaJA}$	45	

ELECTRICAL CHARACTERISTICS (T_{.1} = 25°C unless otherwise noted)

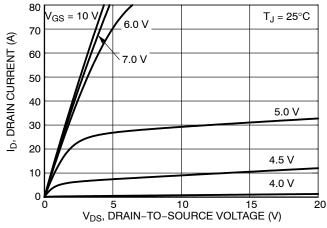
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
OFF CHARACTERISTICS	•				•		
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	600	_	_	V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_J}$	I _D = 10 mA, Referenced to 25°C	-	630	_	mV/°C	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 600 V, T _J = 25°C	-	_	2	μΑ	
Gate-to-Source Leakage Current	I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	_	±100	nA	
ON CHARACTERISTICS							
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 20.5 A, T _J = 25°C	-	48.8	61	mΩ	
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}, I_D = 4.4 \text{ mA}, T_J = 25^{\circ}\text{C}$	2.7	_	4.3	V	
Forward Trans-conductance	9FS	V _{DS} = 20 V, I _D = 20.5 A	-	40.8	-	S	
CHARGES, CAPACITANCES & GATE	RESISTANCE				•		
Input Capacitance	C _{ISS}	V _{DS} = 400 V, V _{GS} = 0 V, f = 250 kHz	-	4176	_	pF	
Output Capacitance	C _{OSS}	1	-	60.4	-	1 !	
Time Related Output Capacitance	C _{OSS(tr.)}	I_D = Constant, V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	939	-		
Energy Related Output Capacitance	C _{OSS(er.)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	101	-		
Total Gate Charge	Q _{G(tot)}	V _{DD} = 400 V, I _D = 20.5 A, V _{GS} = 10 V	-	73.6	-	nC	
Gate-to-Source Charge	Q_{GS}	1	-	20.3	-	1	
Gate-to-Drain Charge	Q_{GD}	1	-	18.9	-		
Gate Resistance	R_{G}	f = 1 MHz	-	0.61	-	Ω	
SWITCHING CHARACTERISTICS					•		
Turn-On Delay Time	t _{d(on)}	$V_{GS} = 0/10 \text{ V}, V_{DD} = 400 \text{ V},$	-	21.6	_	ns	
Rise Time	t _r	$I_D = 20.5 \text{ A}, R_G = 4.7 \Omega$	-	8.64	-		
Turn-Off Delay Time	t _{d(off)}	1	-	76.1	-		
Fall Time	t _f	1	-	2.62	-		
SOURCE-TO-DRAIN DIODE CHARAC	TERISTICS				-	-	
Forward Diode Voltage	V_{SD}	$V_{GS} = 0 \text{ V}, I_{SD} = 20.5 \text{ A}, T_J = 25^{\circ}\text{C}$	-	_	1.2	V	
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, I _{SD} = 20.5 A,	-	416	-	ns	
Reverse Recovery Charge	Q _{RR}	dI/dt = 100 A/μs, V _{DD} = 400 V	_	7405	-	nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

1000

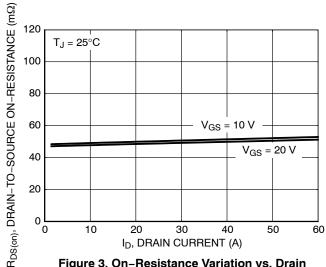
 $V_{DS} = 20 V$



ID, DRAIN CURRENT (A) $T_J = 25^{\circ}C$ $T_J = 150^{\circ}C$ $T_J = -55^{\circ}C$ V_{GS}, GATE-TO-SOURCE VOLTAGE (V)

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics





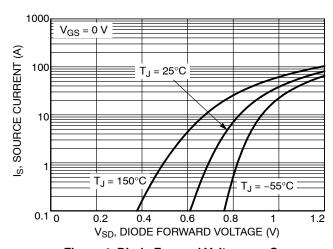
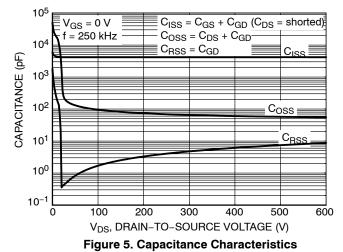


Figure 4. Diode Forward Voltage vs. Source Current



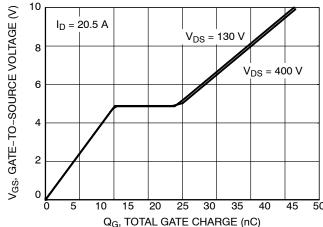


Figure 6. Gate Charge Characteristics

TYPICAL CHARACTERISTICS

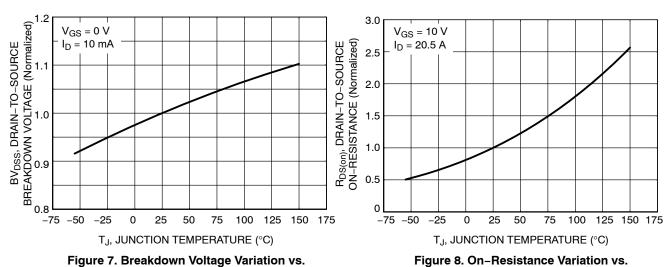


Figure 7. Breakdown Voltage Variation vs. **Temperature**

100 μs

Operation in this Area is

Limited by R_{DS(on)}

T_C = 25°C

 $T_J = 150^{\circ}C$ Single Pulse

100

10

0.1

ID, DRAIN CURRENT (A)

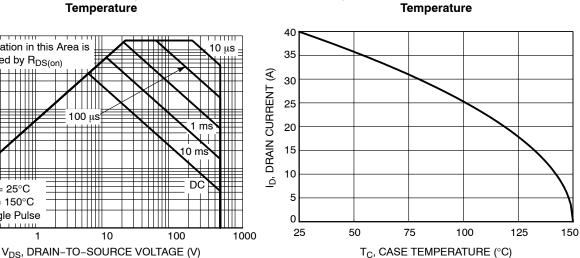
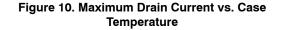


Figure 9. Maximum Safe Operating Area

10



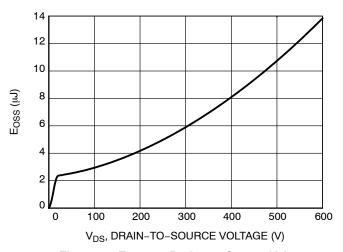


Figure 11. E_{OSS} vs. Drain-to-Source Voltage

TYPICAL CHARACTERISTICS

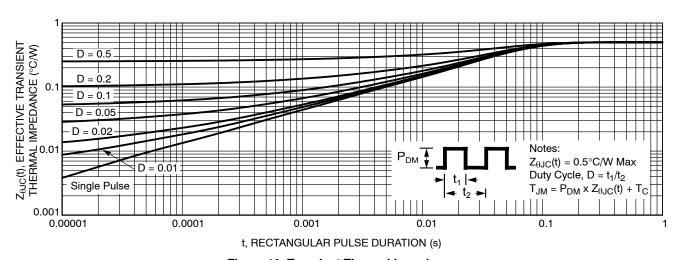
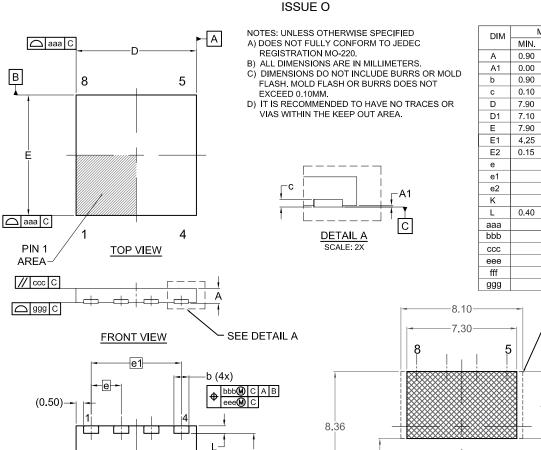


Figure 12. Transient Thermal Impedance

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PACKAGE DIMENSIONS

TDFN4 8x8, 2P CASE 520AB



É1

⊕ fffM C A B

-(0.40)

-(0.40)

-D1-

⊕ fffM C A B

BOTTOM VIEW

e2

(1.03)

E2

(6x)

RECOMMENDED LAND PATTERN

2.00

-1.25 (8X)

2.64

MILLIMETERS

1.00

1.00

0.20

8.00

7.20

8 00

4.35

2.00 BSC 6.00 BSC

3.10 BSC

(2.75) 0.50

0.10

0.10

0.05

0.05

0.10

0.15

4.45

1.28

-KEEP OUT AREA

0.25 0.35

NOM. MAX.

1.10

0.05

1.10

0.30

8.10

7.30 8.10

4.45

0.60

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRIMD.

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